## Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computers

**Marketing Name / Model**
[List multiple models if applicable.]

HP Compaq Elite 8300 SFF PC

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Liteon 320W EPA PSU</td>
<td>3</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>T-15</td>
</tr>
<tr>
<td>Micro shear</td>
<td>170II</td>
</tr>
<tr>
<td>Screwdriver</td>
<td>PH1</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the access panel. (see Figure 1 below)
2. Disconnect the cables from fan duct and the board. (see Figure 2-6 below)
3. Remove ODD or HDD from chassis. (see Figure 7-15 below)
4. Remove PSU from chassis. (see Figure 16 below)
5. Remove front bezel from chassis. (see Figure 17 below)
6. Remove front system fan from chassis. (see Figure 18-19 below)
7. Remove FIO and speaker from chassis. (see Figure 20-22 below)
8. Remove the Memory card from the board. (see Figure 23 below)
9. Remove the CPU from the board. (see Figure 24-26 below)
10. Remove the battery from the system board. (see Figure 27 below)
11. Remove M/B from chassis. (see Figure 28-29 below)
12. Remove PSU cover. (see Figure 30-31 below)
13. Disconnect all the cables and remove the Electrolytic Capacitors. (see Figure 32-44 below)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Figure 1 Remove the access panel:
Figure 2 Disconnect the cables from fan duct

Figure 3 Remove fan duct from the board
Figure 4 Disconnect the cables from the MB

Figure 5 Disconnect CPU Power cable from the MB
Figure 6 Disconnect other PSU cables from the MB

PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
PSG instructions for this template are available at EL-MF877-01
Figure 13 Disconnect SATA cable from second HDD

Figure 14 Press the ODD's latch on ODD cage

Figure 15 Remove second HDD from cage

Figure 16 Remove the PSU from Cage

Figure 17 Remove front panel

Figure 18 Disconnect front system fan cable from MB

PSG instructions for this template are available at EL-MF877-01
Figure 19 Remove front system fan

Figure 20 Disconnect FIO cables from MB

Figure 21 Loose the screws of FIO and remove it

Figure 22 Loose the screws of speaker and remove it

Figure 23 Remove the Memory card from the board

Figure 24 Loose the screws and remove heat sink

PSG instructions for this template are available at **EL-MF877-01**
Figure 25 Rotate the handle and open it up

Figure 26 Remove the CPU from the board

Figure 27 Remove the battery from the system board

Figure 28 Loose the screws of MB from board

Figure 29 Remove M/B from chassis

Figure 30 Remove the screws on the PSU chassis

PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
Figure 31: Lift the cover off the power supply

Figure 32: Remove the four screws on the board

Figure 33: Using Soldering Iron, heat the solder of the cables which connect to the PCA, then remove them

Figure 34: Remove the power supply cable from the power supply

Figure 35: Heat the solder of Electrolytic Capacitors

Figure 36: Remove the Electrolytic Capacitors

PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
Figure 37 Heat the solder of Electrolytic Capacitors greater than 2.5cm in diameter or height

Figure 38 Remove the Electrolytic Capacitors (For Acbel 240W EPA)

Figure 39 Remove the Electrolytic Capacitors (For Acbel 240W STD)

Figure 40 Remove the Electrolytic Capacitors (For Liteon STD PSU)

Figure 41 Remove the Electrolytic Capacitors (For Liteon EPA PSU)

Figure 42 Remove the Electrolytic Capacitors (For Delta EPA PSU)

PSG instructions for this template are available at EL-MF877-01
Figure 43 Remove the Electrolytic Capacitors (For Chicony EPA PSU)

Figure 44 Remove the Electrolytic Capacitors (For Chicony STD PSU)

Figure 45 Remove the Electrolytic Capacitors (For Bestec EPA PSU)

Figure 46 Remove the Electrolytic Capacitors (For Bestec STD PSU)

PSG instructions for this template are available at EL-MF877-01